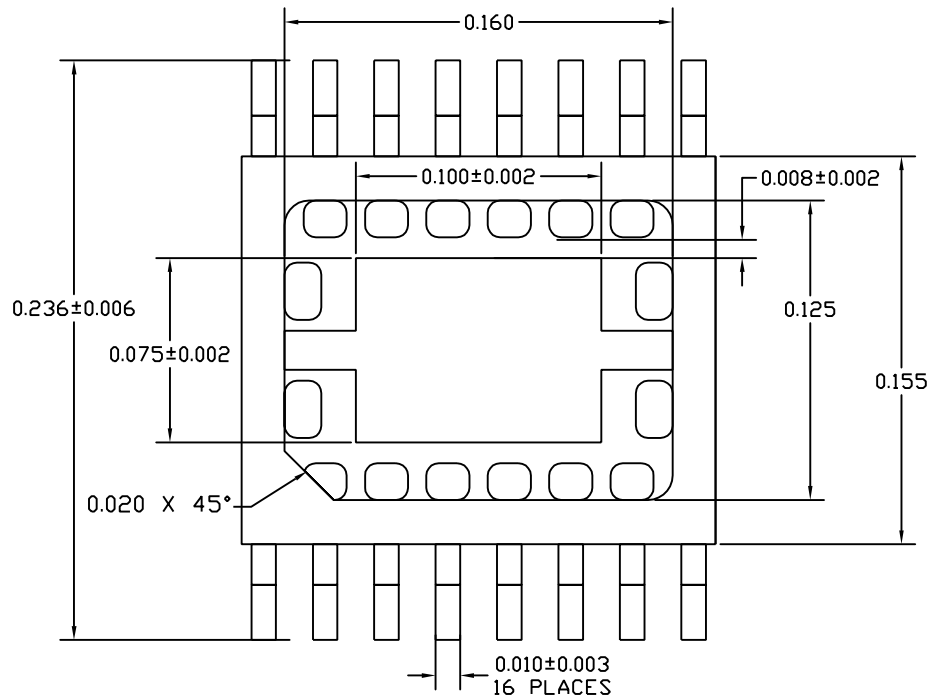
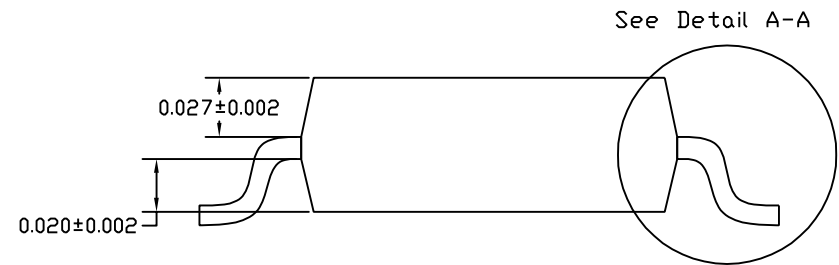
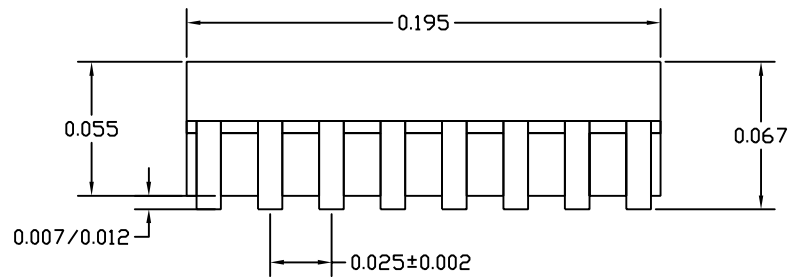
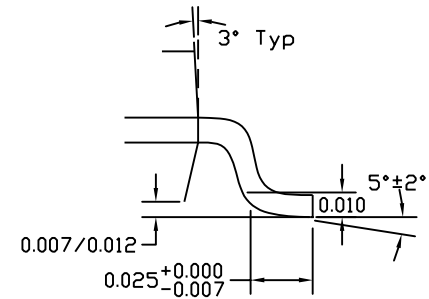


ECN	REV.	DESCRIPTION	DATE	APP'D:
10019	-	INITIAL RELEASE	02/21/01	BF



DETAIL A-A



NOTES:
 BODY : PLASTIC, SEMICONDUCTOR GRADE
 LEAD FRAME : COPPER, OLIN 194
 LEAD FINISH : 50uIN Au, OVER 50uIN NI
 FRAME THICKNESS : 0.008*+/- 0.001"



TITLE: 16 Lead SSOP Open-Pak (0.150" Wide)

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.D.
GEN. TOL: ±0.005	DATE: 11/11/00	APP'D: BF 02/21/01
SSM P/N: PSP161501	DWG. NO.: SSOP16-OP-01	REV.: -